

# Material Declaration Report



Package Type:	SSOP 28L
Pericom Package Code:	H28(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	231.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	9/17/2008

## Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	175.914	OSE	Silica Fused	60676-86-0	90.800	159.7299
			Epoxy Resin 1	Proprietary	3.000	5.2774
			Phenolic Resin	Proprietary	3.000	5.2774
			Epoxy Resin 2	Proprietary	2.000	3.5183
			Aromatic Phosphate	Proprietary	1.000	1.7591
			Carbon Black	1333-86-4	0.200	0.3518
			LEADFRAME	44.769		Copper
			Iron	7439-89-6	2.350	1.0521
			Silver	7440-22-4	0.453	0.2029
			Zinc	7440-66-6	0.111	0.0496
			Phosphorus	7723-14-0	0.065	0.0291
SILICON DIE	5.435		Silicon (Si)	7440-21-3	99.192	5.3908
			Non-hazardous Metal	Proprietary	0.808	0.0439
DIE ATTACH EPOXY	0.501		Silver	7440-22-4	76.000	0.3804
			Acrylic Resin	Proprietary	8.000	0.0400
			Acrylate	Proprietary	5.500	0.0275
			Polybutadiene derivative	Proprietary	5.500	0.0275
			Epoxy resin	Proprietary	2.500	0.0125
			Additive	Proprietary	1.000	0.0050
			Butadiene copolymer	Proprietary	1.000	0.0050
			Peroxide	Proprietary	0.500	0.0025
GOLD WIRE	1.011		Gold(Au)	7440-57-5	99.990	1.0113
			Impurities	-	0.010	0.0001
SOLDER PLATING	3.870		Tin (Sn)	7440-31-5	99.990	3.8697
			Impurity	-	0.010	0.0004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.</p> <p>X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>							